

REMARKS

Reconsideration of the above-identified patent application, as amended, is respectfully requested. The present amendment is responsive to the Office Action mailed August 14, 2001. A petition for an extension of time in which to respond to the Office Action accompanies this amendment.

This application is a divisional of prior Application No. 09/254,119.

By the present amendment, claims 16-26 are pending in the application.

Support For Claims

Claims 16 and 20 correspond to semiconductor device claim 16 presented in parent Application No. 09/254,119. The method steps of claim 16 corresponds to the method steps of original claim 7. The method steps of claim 20 correspond to the method steps of original claim 10.

Claims 17 and 21 correspond to semiconductor device claim 17 presented in parent Application No. 09/254,119. The method steps of claim 17 corresponds to the method steps of original claim 7. The method step of claim 21 corresponds to the method steps of original claim 10.

Additional support for new independent claims 16 and 20 may be found in the specification at page 5, lines 6-18 and page 9, lines 27-29; and in the drawings at Fig. 2 and Fig. 3.

Page 9, lines 14-18 disclose at least one layer laminated to the layer of the electrode material to avoid deterioration of the bonding.

Page 9, lines 27-28 disclose the peripheral dimensions substantially the same as or somewhat larger than.

Figs. 2 and 3 illustrate the at least one layer at 6, 7; the electrode material 5, and the electrode 8 which comprises 5, 6 and 7. Page 9, lines 6-9 disclose an Al alloy layer as the electrode material with an Ni layer and a Cu layer laminated to the Al alloy layer so as to firmly bond the semiconductor device to the substrate by the solder bump.

New independent claims 17 and 21 the same as new independent claims 16 and 20 with the additional limitation that "at least one of the at least one layer (6, 7) has a thickness which is smaller than that of the electrode material (5)". This is illustrated in Figs. 2 and 3 of the drawings.

New dependent claim 18 corresponds to canceled dependent claim 8.

New dependent claim 19 corresponds to canceled dependent claim 9.

New dependent claims 22-26 correspond to canceled dependent claims 11-15, respectively.

New matter is not being presented by the present amendment.

§112, ¶2

Claims 7-15 were rejected under 35 U.S.C. §112, second paragraph, as being indefinite.

The Office Action objected to the phrase "low melting point" as modifying "metal balls".

In response to this rejection, new claims 16-26 of the present amendment do not use the phrase "low melting point".

In view of the present amendment, it is respectfully requested that the rejection under 35 U.S.C. §112, second paragraph, be withdrawn.

**§102(b)**

Claims 7-15 were rejected under 35 U.S.C. §102(b) as being unpatentable over Japan No. 4-65130 to Okuyama.

This rejection, as applied to new claims 16-26, is respectfully traversed.

It is submitted that Japan No. 4-65130 to Okuyama does not disclose or suggest the structural arrangement of the semiconductor device recited in new independent claims 16, 17, 20 and 21 of the present amendment.

It is therefore submitted that new independent claims 16, 17, 20 and 21, and all claims dependent thereon, are patentable over Japan No. 4-65130 to Okuyama.

**Drawings**

Form PTO-948, Notice of Draftsperson Patent Drawing Review, was not attached to the Office Action.

Applicants respectfully request to be advised of the status of the drawings in the next communication from the Patent and Trademark Office.

CONCLUSION

It is submitted that in view of the present amendment and foregoing remarks, the application is now in condition for allowance. It is therefore respectfully requested that the application, as amended, be allowed and passed to issue.

Respectfully submitted,

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